



## Material Content Data Sheet



<b>Sales Product Name</b>		IPD031N06L3 G		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA000505426						
<b>Package</b>		PG-TO252-3-11		<b>Weight*</b>		373.28 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.184	1.39	1.39	13888	13888
leadframe	non noble metal	iron	7439-89-6	0.234	0.06		628	
	inorganic material	phosphorus	7723-14-0	0.070	0.02		188	
	non noble metal	copper	7440-50-8	234.187	62.74	62.82	627373	628189
wire	non noble metal	aluminium	7429-90-5	10.000	2.68	2.68	26790	26790
encapsulation	organic material	carbon black	1333-86-4	1.158	0.31		3102	
	plastics	epoxy resin	-	20.265	5.43		54289	
	inorganic material	silicondioxide	60676-86-0	94.376	25.28	31.02	252830	310221
leadfinish	non noble metal	tin	7440-31-5	3.740	1.00	1.00	10019	10019
plating	non noble metal	nickel	7440-02-0	0.091	0.02		243	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.02	1	244
solder	noble metal	silver	7440-22-4	0.099	0.03		266	
	non noble metal	tin	7440-31-5	0.080	0.02		213	
	non noble metal	lead	7439-92-1	3.796	1.02	1.07	10170	10649
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

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